



<b>Title of Change:</b>	Product Transfer of Thin Quad Flat Pack (TQFP) from J-Device Kitakami to J-Device Usuki.			
<b>Proposed first ship date:</b>	7 September 2016			
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Fumio.Baba@onsemi.com>			
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office			
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office			
<b>Type of notification:</b>	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact &lt;PCN.Support@onsemi.com&gt;.</p>			
<b>Change Part Identification:</b>	Affected products will be identified with marking lot number and ASSY LOC CODE "K1" in MPN Label			
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____			
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s) J-Devices Corporation			
<b>Description and Purpose:</b>				
<p>This is a Final Notification to announce the plan to transfer the assembly site of Thin Quad Flat Pack (TQFP) products from J-Device Kitakami to J-Device Usuki. The assembly site of Thin Quad Flat Pack (TQFP) will move from J-Device Kitakami to J-Device Usuki, Japan.</p> <p>The current material used, process flow, process control and product specification such as visual, physical dimension, electrical characteristic remain the same.</p> <p><b>Note:</b> Current test site for the affected products doesn't change.</p>				
<b>Reliability Data Summary:</b>				
QV DEVICE NAME: LC823430TA-2H PACKAGE: TQFP128				
Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008hrs	0/150
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/90
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/300
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/90
THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs	0/90
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	192hrs	0/90
SAT				0/30
PUD	12MON49370E	After TC 500c		0/5
SD	JSTD002	Ta = 245C, 10 sec		0/ 9



**Electrical Characteristic Summary:**  
 Electrical characteristics are not impacted.

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
LC823425-12G1-H	LC823430TA-2H
LC823425-12G1-LR-H	LC823430TA-2H
LC823430TA-2H	LC823430TA-2H
LC823432TAK-2H	LC823430TA-2H

**List of Affected Customer Specific Parts:**

*NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "[Custom PCN for Selected Company Button](#)" in the Document Analysis page of PCMS/PCN Alert.*